



RE130-LF

- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Surface with solder stop mask
- Hole spacing 2.00 x 2.00 mm
- 44 x 42 soldering pads 1.60 x 1.60 mm
- Hole diameter 1.00 mm
- Working temperature max. 150 °C
- Soldering bath proof: 260 °C > 50 sec.
- Size 90.17 x 95.89 mm